

MA2J113 (MA113)

Silicon epitaxial planar type

For switching circuits

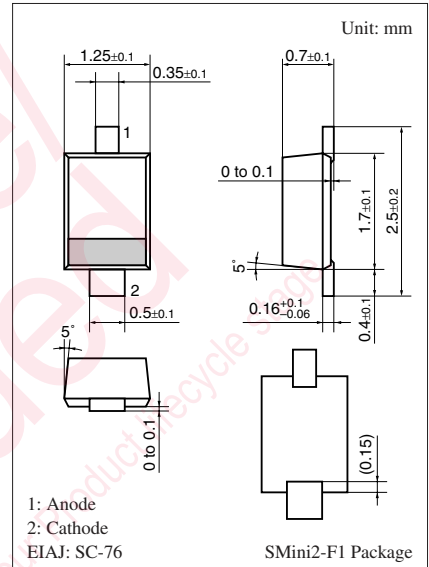
■ Features

- Allowing high-density mounting
- Ensuring the forward current (Average) capacity $I_{F(AV)} = 200$ mA
- High breakdown voltage: $V_R = 80$ V

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	80	V
Maximum peak reverse voltage	V_{RM}	80	V
Forward current (Average)	$I_{F(AV)}$	200	mA
Peak forward current	I_{FM}	600	mA
Non-repetitive peak forward surge current *	I_{FSM}	1	A
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *: $t = 1$ s



Marking Symbol: 1D

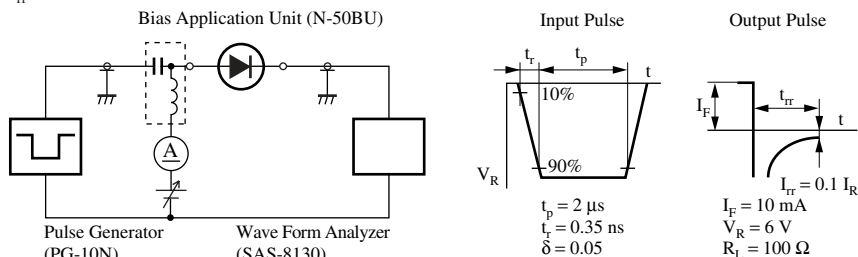
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 200$ mA			1.1	V
Reverse current	I_{R1}	$V_R = 15$ V			50	nA
	I_{R2}	$V_R = 75$ V			500	nA
	I_{R3}	$V_R = 75$ V, $T_a = 100^\circ\text{C}$			100	μA
Terminal capacitance	C_t	$V_R = 0$ V, $f = 1$ MHz			4	pF
Reverse recovery time *	t_{rr}	$I_F = 10$ mA, $V_R = 6$ V $I_{rr} = 0.1 I_R$, $R_L = 100 \Omega$			10	ns

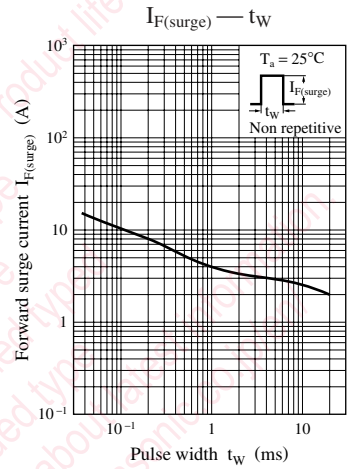
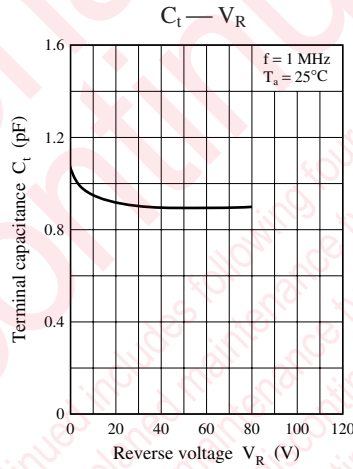
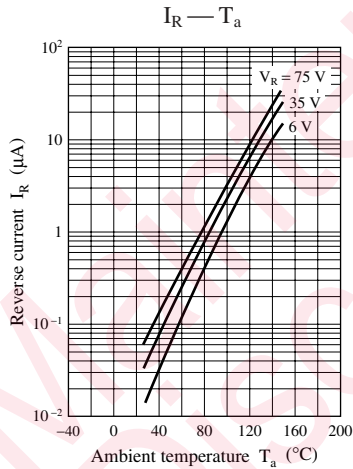
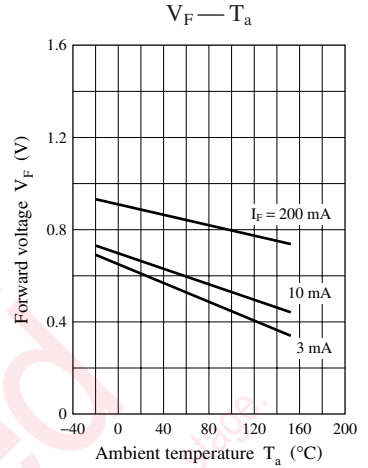
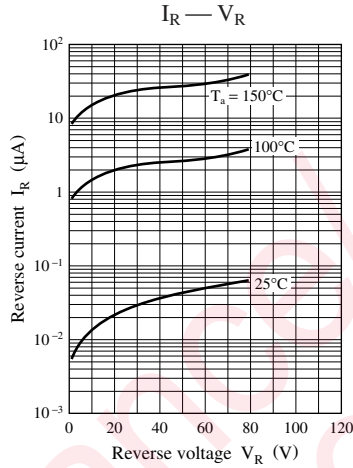
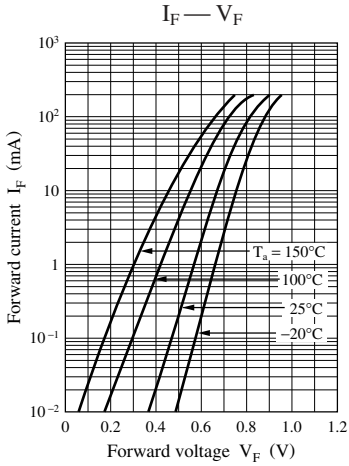
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz.

3. *: t_{rr} measurement circuit



Note) The part number in the parenthesis shows conventional part number.



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